

FIG. 2

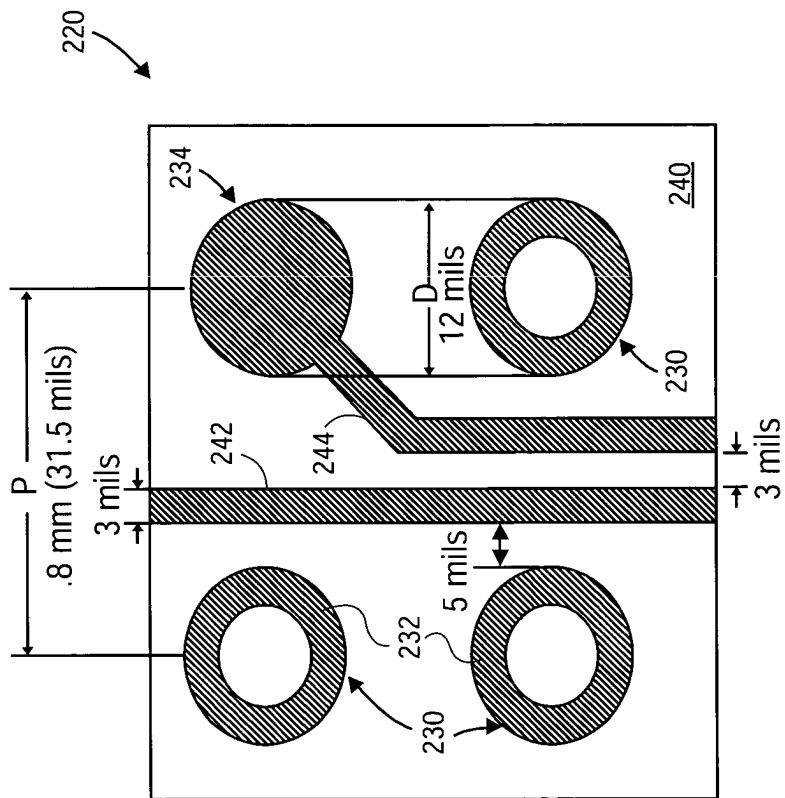
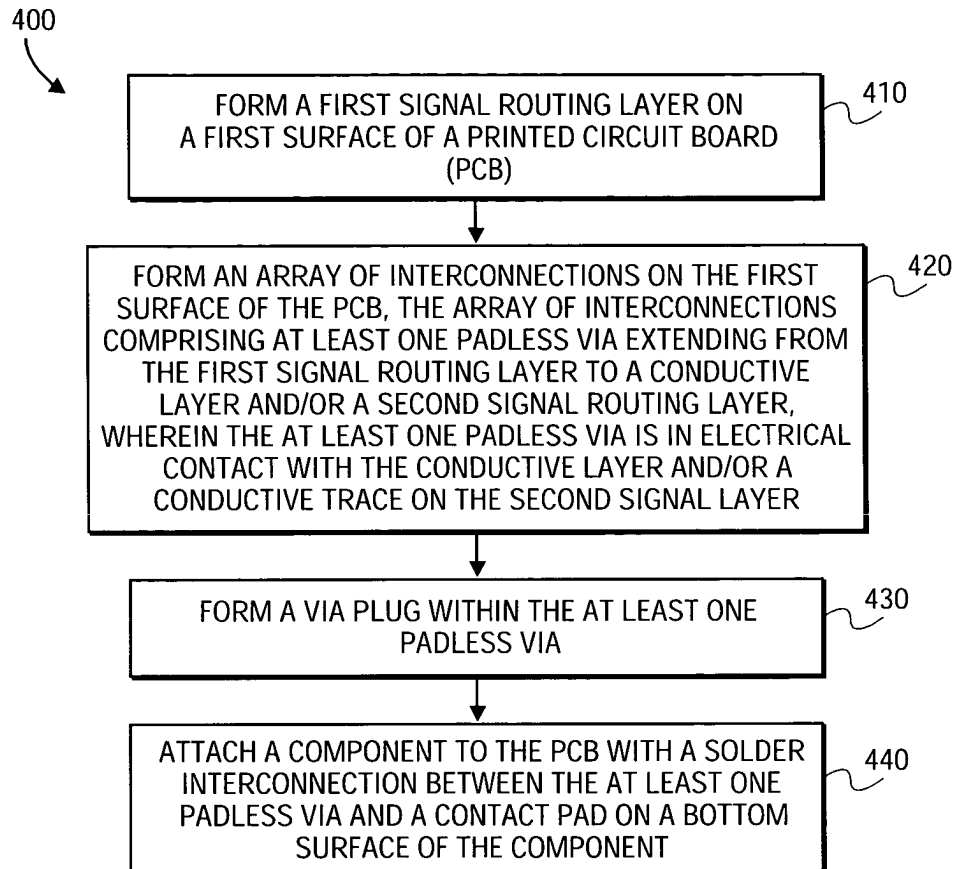
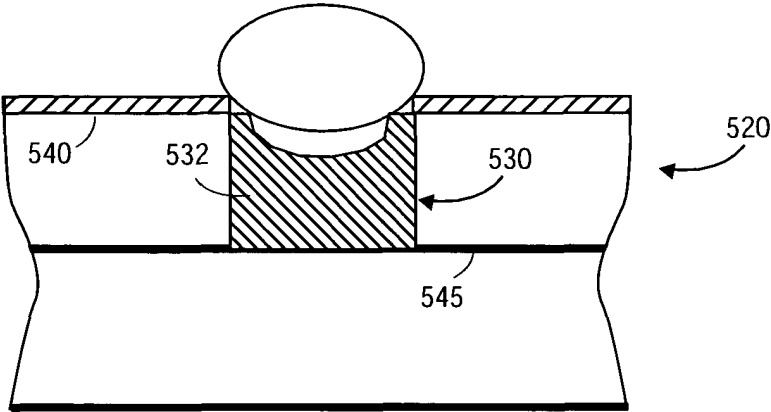


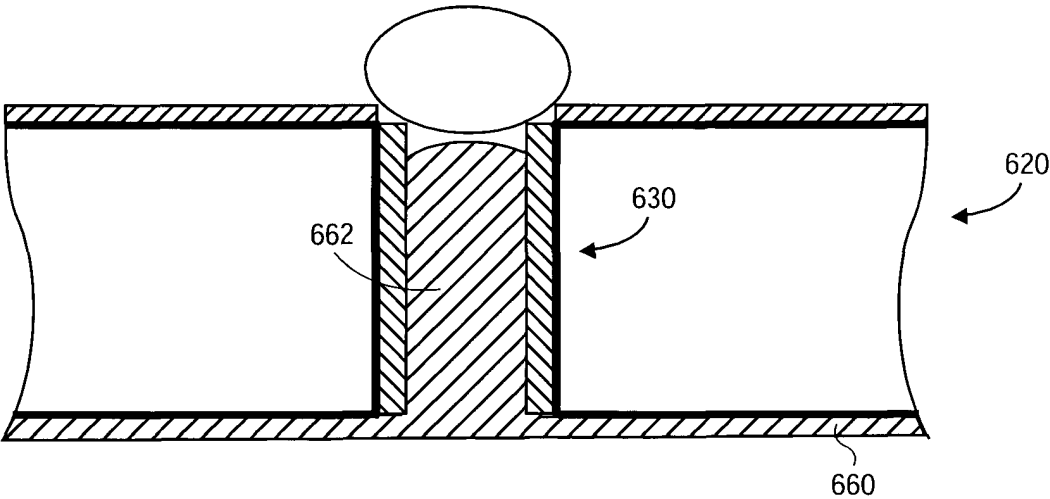
FIG. 3



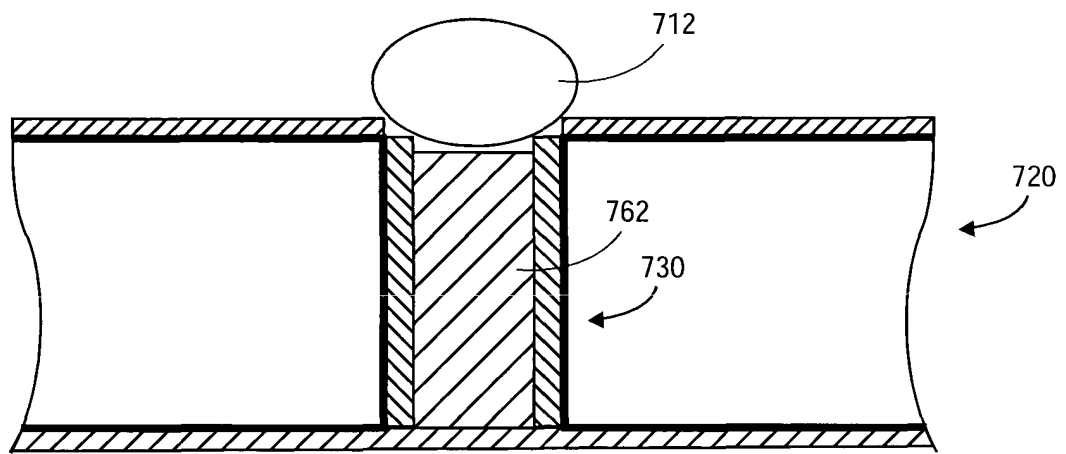
**FIG. 4**



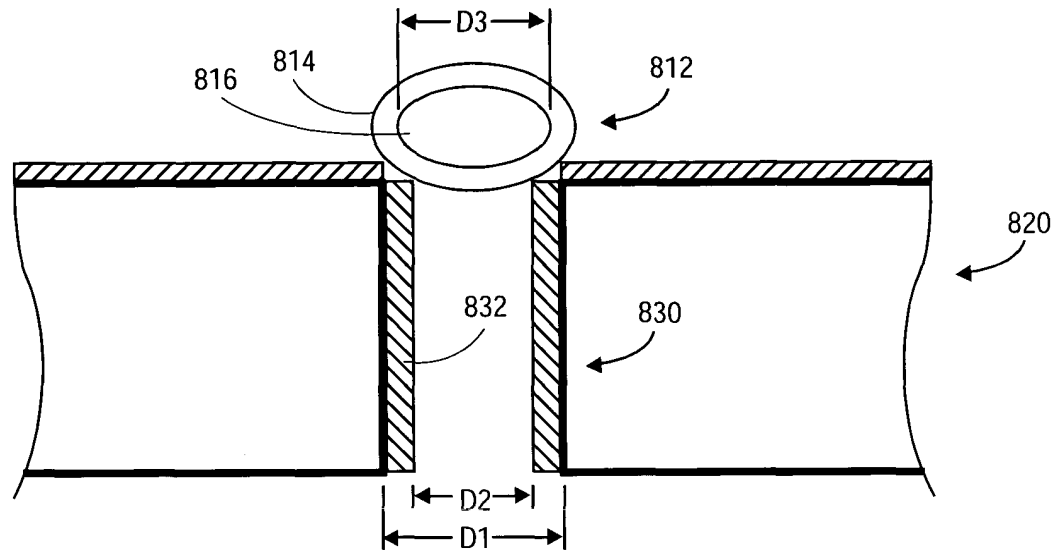
**FIG. 5**



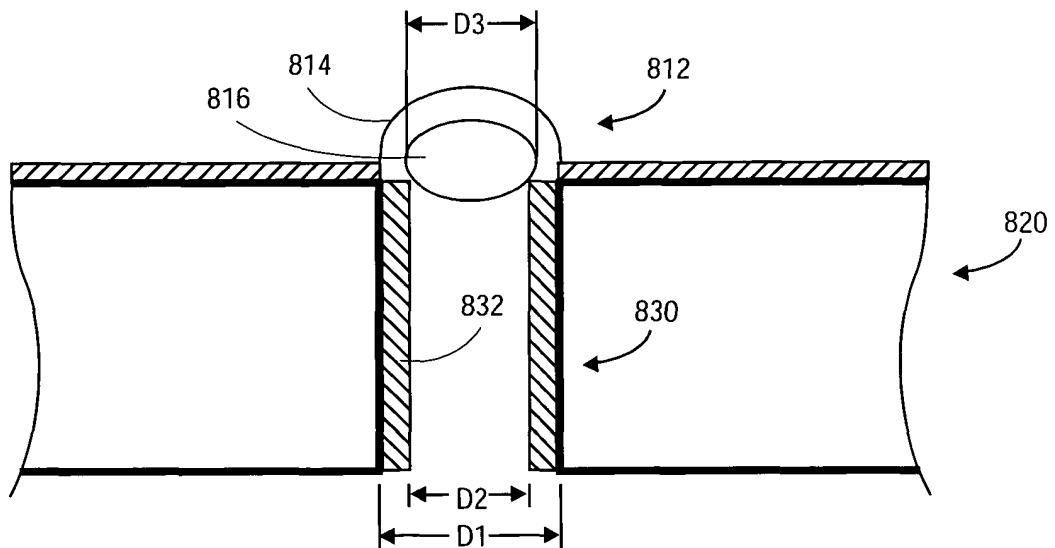
**FIG. 6**



**FIG. 7**



**FIG. 8A**



**FIG. 8B**

Routeable Traces Between Interconnections Trace/Space = 3/3 mils, Trace-Via spacing = 5 mils					
Interconnection		Component Pitch (mm)			
Type	Diameter (mils)	0.5	0.75	0.8	1
Padless via	6	1	2	3	4
Padless via	8	0	2	2	4
Padless via	12	0	1	2	3
Padless via	18	X	0	1	2
Contact Pad	24	X	X	0	1
Contact Pad	32	X	X	X	0
X = overlap					

FIG. 9